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(54) **MICROELECTRONIC SUBSTRATES WITH THERMALLY CONDUCTIVE PATHWAYS AND METHODS OF MAKING SAME**

MIKROELEKTRONISCHE SUBSTRATE MIT THERMISCH LEITENDEN EINSÄTZEN UND VERFAHREN ZU DEREN HERSTELLUNG

SUBSTRATS MICRO-ELECTRONIQUES INCLUANTS DES INSERTS THERMOCONDUCTEURS ET LEURS PROCÉDES DE FABRICATION

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